

# FAST CORE NO CLEAN CORED WIRE SOLDER

## **FEATURES**

- Enhanced Wetting Properties
- Solder Applications
- Wide Process Window
- Clear, Hard Residues

### DESCRIPTION

Fast Core wire solder was designed for applications requiring greater activity than no clean or RMA fluxed solders. Fast Core provides excellent wetting, shiny solder joints and a wide process window on a variety of surface finishes. Fast Core flux promotes good thermal transfer, offering excellent solder penetration into plated through holes or surface mount interconnections. Fast Core wire solder produces low-to-medium, hard, clear post-process residues. Fast Core IPC flux classification is ROM1 and may require removal from sensitive electronics.

## STANDARD AVAILABILITY

Fast Core is available in Sn/Pb, Sn/Cu, SAC and SN100C<sup>®</sup> alloys. Other alloys, diameters and spool sizes may be available upon request.

#### **APPLICATION**

Best results are obtained with solder iron tip temperature between  $300^{\circ} - 400^{\circ}C$  (575° - 750°F) for leaded alloys and 370° - 425°C (700° - 800°F) for lead-free and SN100C® alloys. If additional flux is required AIM NC280 flux is recommended.



#### **HANDLING & STORAGE**

Time	Temperature			
7 Years	< 85°F (< 29°C)			

Store cored wire in a clean, dry area away from moisture and sunlight. Do not freeze this product.

## **CLEANING**

Fast Core can be cleaned with many commercially available flux removers. Contact AIM for specific information.

## SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying SDS for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

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## **TECHNICAL DATA SHEET**



## **TEST DATA SUMMARY**

Name	Test Method		Results
IPC Flux Classification	J-STD-004	ROM1	
IPC Flux Classification	J-STD-004B 3.3.1	ROM1	
Name	Test Method	Results	Image
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	FASTCORE CONTROL
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	Before After   Image: Constraint of the second seco
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	Br 0.00% Cl: 0.03% Typical	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No fluoride	
Surface Insulation Resistance	J-STD-004 3.4.1.4 IPC-TM-650 2.6.3.3	PASS	
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	All measurements on all test patterns exceed the 100 MΩ	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	224 KOH / g Flux Typical	
Visual	J-STD-004B 3.4.2.5	PASS	
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	

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